

MECHANICAL CASE OUTLINE

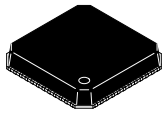
PACKAGE DIMENSIONS

ON Semiconductor®

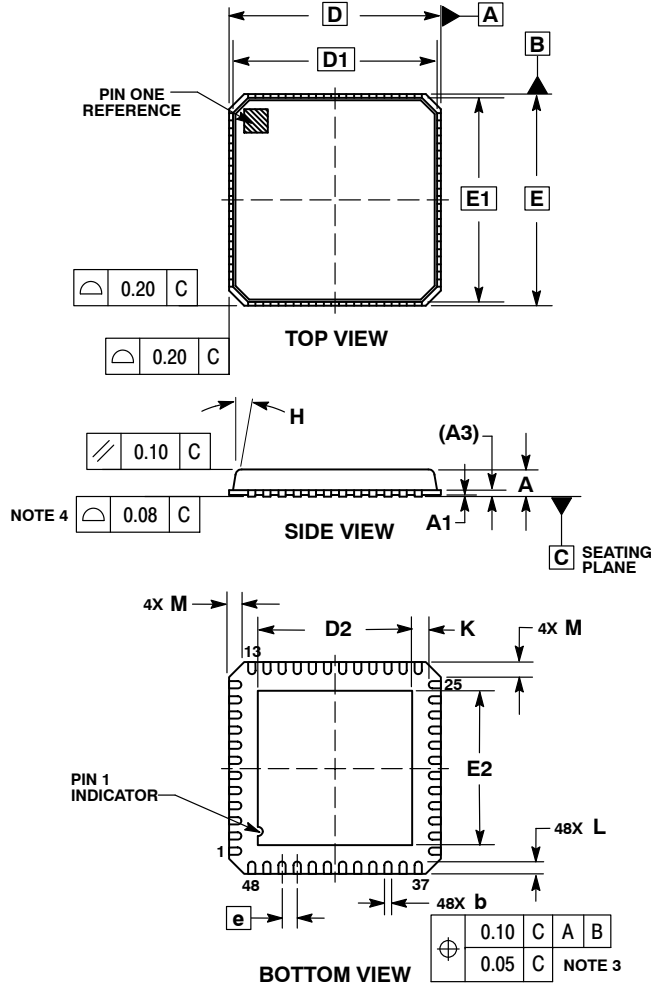


LFCSP48 7x7, 0.5P
CASE 932AD-01
ISSUE A

DATE 23 JAN 2009



SCALE 2:1

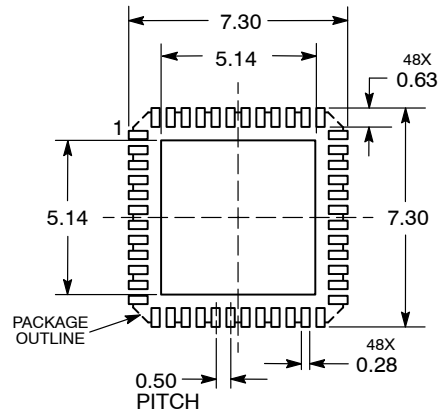


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSIONS: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20	REF
b	0.18	0.30
D	7.00	BSC
D1	6.75	BSC
D2	4.95	5.25
E	7.00	BSC
E1	6.75	BSC
E2	4.95	5.25
e	0.50	BSC
H	---	12°
K	0.20	---
L	0.30	0.50
M	---	0.60

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	LFCSP48, 7x7, 0.5P	PAGE 1 OF 1

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